

METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES  
HAVING AN ENCAPSULATED INSULATION LAYER

**Abstract of the Disclosure**

An integrated circuit device is manufactured by forming an insulating layer on a substrate. A capping layer is formed on the insulating layer and both the capping layer and the insulating layer are patterned. Insulating spacers are formed on sidewalls of the insulating layer so that the insulating spacers, the capping layer, and  
5 the substrate enclose the insulating layer.